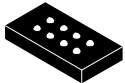


MECHANICAL CASE OUTLINE

PACKAGE DIMENSIONS

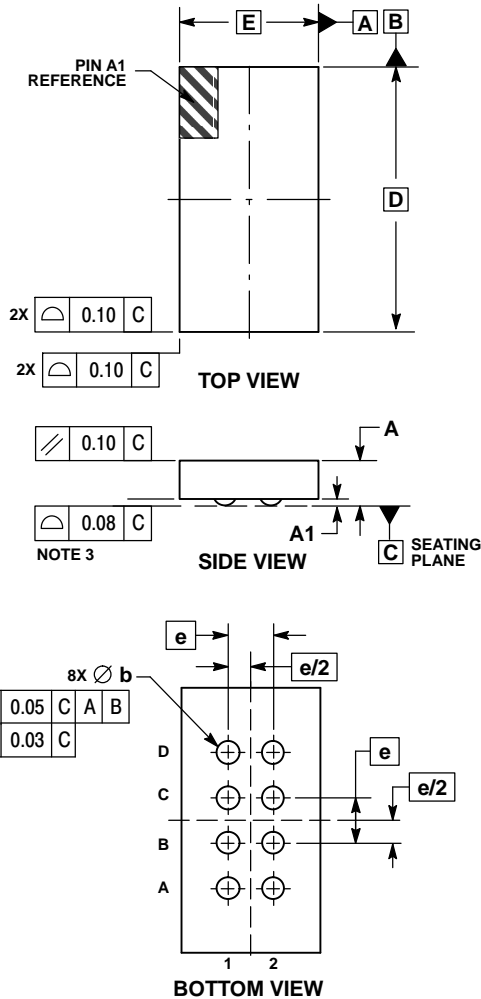
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SCALE 4:1

WLCSP8, 2.92x1.53
CASE 567LC
ISSUE A

DATE 18 MAR 2015

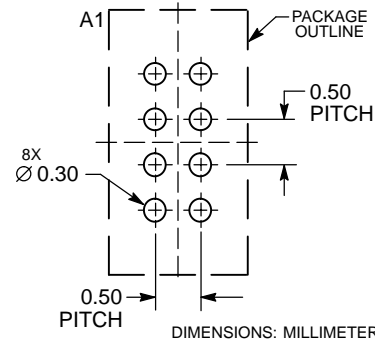


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO THE SPHERICAL CROWNS OF THE SOLDER BALLS.

DIM	MILLIMETERS	
	MIN	MAX
A	—	0.50
A1	0.03	0.13
b	0.25	0.35
D	2.92 BSC	
E	1.53 BSC	
e	0.50 BSC	

RECOMMENDED SOLDERING FOOTPRINT*



*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

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NEW STANDARD:		
DESCRIPTION:	WLCSP8, 2.92X1.53	PAGE 1 OF 2

